

L Number	Hits	Search Text	DB	Time stamp
1	1	(rta or rapid near2 annealer).ti. and tube and reactor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 08:45
2	220	(rta or rapid near thermal near anneal\$3) and tube and reactor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 08:51
3	302	(rta or rapid near thermal near anneal\$3) near5 (apparatus or housing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 08:51
4	282	(rta or rapid near thermal near anneal\$3) near3 (apparatus)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 08:51
5	42	(rta or rapid near thermal near anneal\$3) near3 (apparatus) and tube	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 09:10
6	22	(rta or rapid near thermal near anneal\$3 or rtp) same tube same reactor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 09:14
7	29	reactor near2 (slot or opening) same (wafer or substrate) near5 (position or positioning or positioned or alignment or align or aligning or locating or location)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 09:16
-	17342	(rta or rtp or thermal near2 process\$3 or heat near2 process\$3 or anneal or annealing or annealer) and (position or positioner or positioning or aligning or locating or locator or locator or positioned or placement or (distance or separation or separator) near3 (lamp or heat or source or light)) near5 (wafer or tray or holder or chuck or carrier or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 08:45
-	2066	(rta or rtp or thermal near2 process\$3 or heat near2 process\$3 or anneal or annealing or annealer) same (position or positioner or positioning or aligning or locating or locator or locator or positioned or placement or (distance or separation or separator) near3 (lamp or heat or source or light)) near5 (wafer or tray or holder or chuck or carrier or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 14:38
-	114	(rta or rtp or thermal near2 process\$3 or heat near2 process\$3 or anneal or annealing or annealer) same (position or positioner or positioning or aligning or locating or locator or locator or positioned or placement or (distance or separation or separator) near3 (lamp or heat or source or light)) near5 (wafer or tray or holder or chuck or carrier or substrate) near10 (groove or notch or c or guide or grooved or notched)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 14:42

-	39	(rta or rtp or thermal near2 process\$3 or heat near2 process\$3 or anneal or annealing or annealer) same (position or positioner or positioning or aligning or locating or locator or locater or positioned or placement or (distance or separation or separator) near3 (lamp or heat or source or light)) near5 (wafer or tray or holder or chuck or carrier or substrate) near10 (groove or notch or c near shape\$2 or guide or grooved or notched)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 15:30
-	1035	(rta or rtp or rapid adj thermal).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/05 15:30
-	114	(rta or rtp or rapid adj thermal).ti. and (position or positioning or locating or locator or positioner or groove or guide or distance or spacing) near4 (wafer or substrate or tray or holder or carrier or chuck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:25
-	4	semiconductor near2 (processing or fabrication or heating or coating or process) and (substrate or wafer) near2 (holder or carrier or boat or chuck) near2 (positioner or positioned or aligned or aligner or positioning or placement) near4 (groove or notch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:28
-	24	semiconductor and (substrate or wafer) near2 (holder or carrier or boat or chuck or tray) near2 (positioner or positioned or aligned or aligner or positioning or placement) near8 (groove or notch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 09:30
-	92	semiconductor and (substrate or wafer) near2 (holder or carrier or boat or chuck or tray) near8 (positioner or positioned or aligned or aligner or positioning or placement) near8 (groove or notch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 12:15
-	125	(substrate or wafer) near10 (holder or carrier or boat or chuck or tray) near10 (positioner or positioned or aligned or aligner or positioning or placement) near10 (discrete or kit or attachable or detachable or separate or nonintegral or non-integral)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 12:18
-	576	257/E21.324.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 12:19
-	78	257/E21.324.ccls. and (wafer or substrate) near6 (positioning or position or positioner or positioned or locator or placement or secured or alignment or aligning)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 13:15
-	48	(wafer or substrate) near2 (tray or carrier or holder) near5 (inserting or insertion or insert) near6 (groove or notch or guide or guiding or grooved)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 13:25
-	166	438/663.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 13:25

-	183	(rta or rtp or anneal or annealer or furnace or diffusion or diffuser or rie or pecvd or chamber or tube) and (wafer or substrate) near4 (boat or tray or holder or carrier or chuck) near5 (insertion or insert or inserting or loading or loaded or load) near10 (groove or grooved or track or guide or guided or guiding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/07 16:35
-	176	(rta or rtp or anneal or annealer or furnace or diffusion or diffuser or rie or pecvd or chamber or tube) and (wafer or substrate) near3 (boat or tray or holder or carrier or chuck) near5 (insertion or insert or inserting or loading or loaded or load) near10 (groove or grooved or track or guide or guided or guiding or notch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 10:11
-	2	5820367.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/08 10:11
-	5	5820367.URPN.	USPAT	2004/01/08 10:11